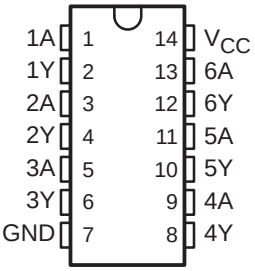
The SN54LS07 and SN74LS17 are obsolete and are no longer supplied.

SN54LS07, SN74LS07, SN74LS17
HEX BUFFERS/DRIVERS
WITH OPEN-COLLECTOR HIGH-VOLTAGE OUTPUTS

SDLS021C − MAY 1990 − REVISED FEBRUARY 2004

- **Convert TTL Voltage Levels to MOS Levels**
- **High Sink-Current Capability**
- **Input Clamping Diodes Simplify System Design**
- **Open-Collector Driver for Indicator Lamps and Relays**

SN54LS07 . . . J PACKAGE
SN74LS07, SN74LS17 . . . D, DB, N, OR NS PACKAGE
(TOP VIEW)



description/ordering information

These hex buffers/drivers feature high-voltage open-collector outputs to interface with high-level circuits or for driving high-current loads. They are also characterized for use as buffers for driving TTL inputs. The ’LS07 devices have a rated output voltage of 30 V, and the SN74LS17 has a rated output voltage of 15 V. The maximum sink current is 30 mA for the SN54LS07 and 40 mA for the SN74LS07 and SN74LS17.

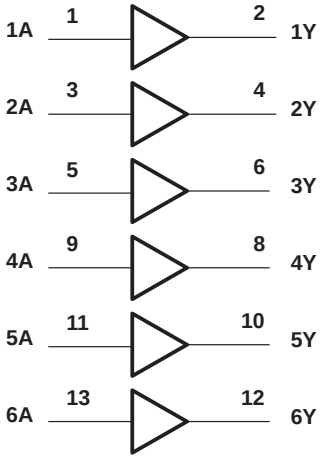
These circuits are compatible with most TTL families. Inputs are diode-clamped to minimize transmission-line effects, which simplifies design. Typical power dissipation is 140 mW, and average propagation delay time is 12 ns.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP − N	Tube	SN74LS07N	SN74LS07N
	SOIC − D	Tube	SN74LS07D	LS07
		Tape and reel	SN74LS07DR	
	SOP − NS	Tape and reel	SN74LS07NSR	74LS07
	SSOP − DB	Tape and reel	SN74LS07DBR	LS07

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

logic diagram (positive logic)



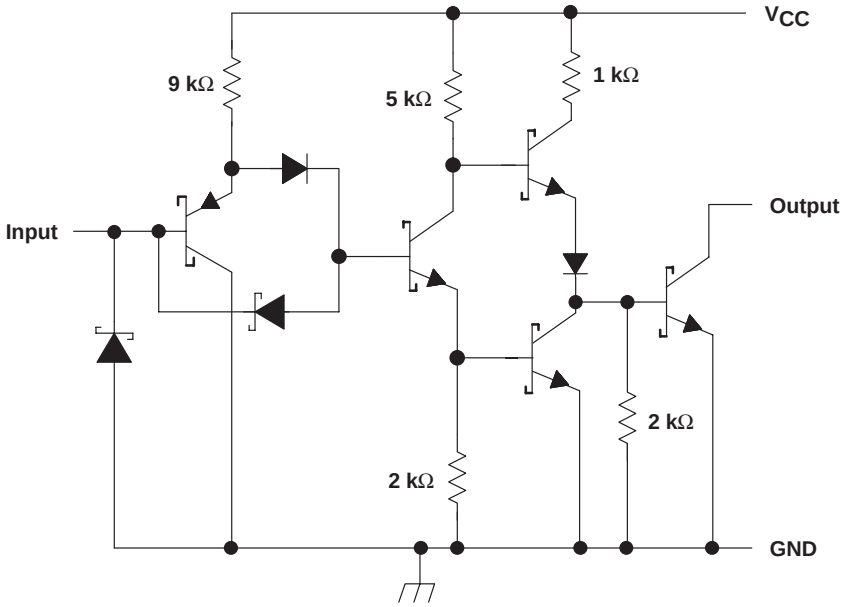
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

The SN54LS07 and SN74LS17 are obsolete and are no longer supplied.

schematic (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC}	7 V
Input voltage, V_I (see Note 1)	7 V
Output voltage, V_O (see Notes 1 and 2): SN54LS07, SN74LS07	30 V
SN74LS17	15 V
Package thermal impedance, θ_{JA} (see Note 3): D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.
2. This is the maximum voltage that should be applied to any output when it is in the off state.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54LS07			SN74LS07 SN74LS17			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.8			0.8	V
V_{OH}	High-level output voltage	’LS07			30			30	V
		SN74LS17						15	
I_{OL}	Low-level output current				30			40	mA
T_A	Operating free-air temperature		−55		125	0		70	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS‡			SN54LS07		SN74LS07 SN74LS17		UNIT
				MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −12 mA			−1.5		−1.5	V
I_{OH}	V_{CC} = MIN,	V_{IH} = 2 V	’LS07, V_{OH} = 30 V		0.25		0.25	mA
			SN74LS17, V_{OH} = 15 V				0.25	
V_{OL}	V_{CC} = MIN,	V_{IL} = 0.8 V	I_{OL} = 16 mA		0.4		0.4	V
			I_{OL} = MAX§		0.7		0.7	
I_I	V_{CC} = MAX,	V_I = 7 V			1		1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.4 V			20		20	µA
I_{IL}	V_{CC} = MAX,	V_I = 0.4 V			−0.2		−0.2	mA
I_{CCH}	V_{CC} = MAX				14		14	mA
I_{CCL}	V_{CC} = MAX				45		45	mA

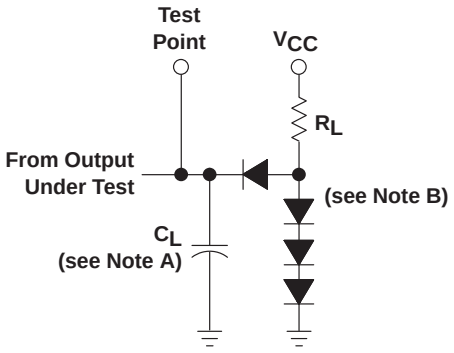
‡ For conditions shown as MIN or MAX, use the appropriate value specified under *recommended operating conditions*.
§ I_{OL} = 30 mA for SN54 series parts and 40 mA for SN74 series parts.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

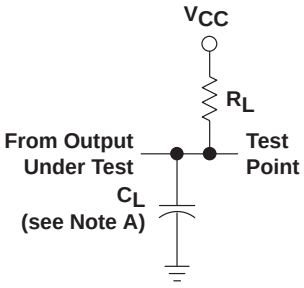
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A	Y	R_L = 110 Ω,	C_L = 15 pF		6	10	ns
t_{PHL}						19	30	

The SN54LS07 and SN74LS17 are obsolete and are no longer supplied.

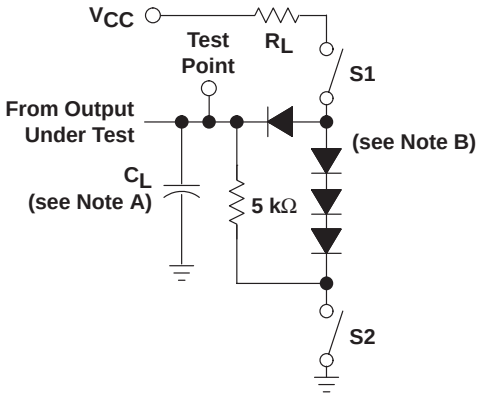
PARAMETER MEASUREMENT INFORMATION



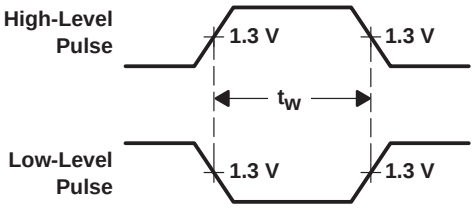
LOAD CIRCUIT
FOR 2-STATE TOTEM-POLE OUTPUTS



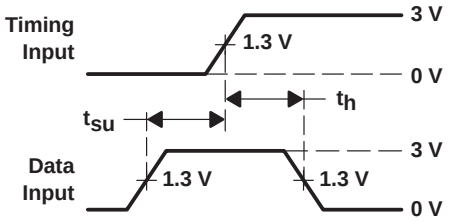
LOAD CIRCUIT
FOR OPEN-COLLECTOR OUTPUTS



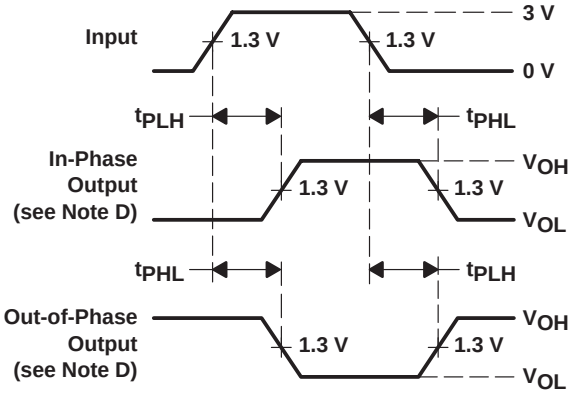
LOAD CIRCUIT
FOR 3-STATE OUTPUTS



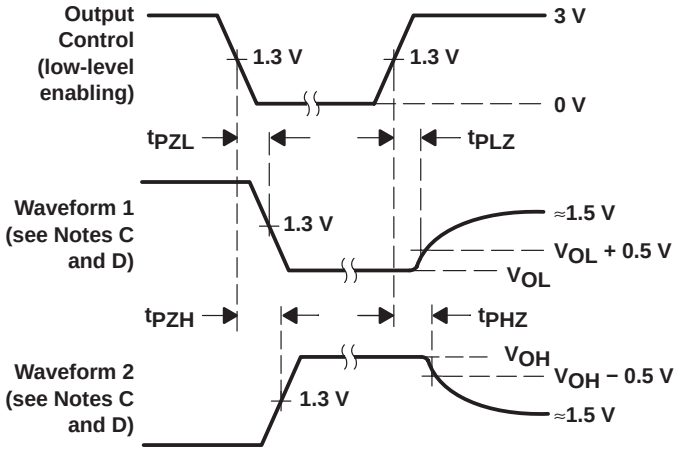
VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
B. All diodes are 1N3064 or equivalent.
C. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
D. S1 and S2 are closed for t_{PLH}, t_{PHL}, t_{PHZ}, and t_{PLZ}; S1 is open and S2 is closed for t_{PZH}; S1 is closed and S2 is open for t_{PZL}.
E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
F. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O \approx 50\ \Omega$, $t_r \le 1.5$ ns, $t_f \le 2.6$ ns.
G. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS07D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS07	Samples
SN74LS07DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI	0 to 70		
SN74LS07DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS07	Samples
SN74LS07DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS07	Samples
SN74LS07DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS07	Samples
SN74LS07DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS07	Samples
SN74LS07DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS07	Samples
SN74LS07DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS07	Samples
SN74LS07DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS07	Samples
SN74LS07N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS07N	Samples
SN74LS07NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS07N	Samples
SN74LS07NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS07	Samples
SN74LS07NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS07	Samples
SN74LS07NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS07	Samples
SN74LS17D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN74LS17N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

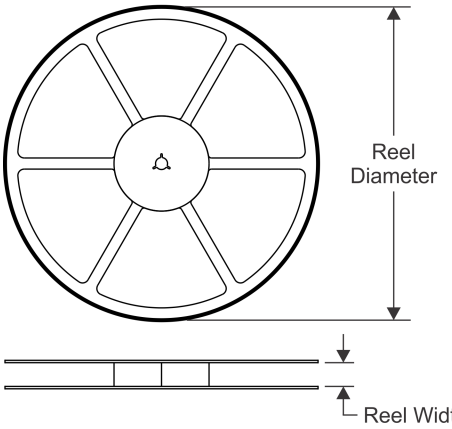
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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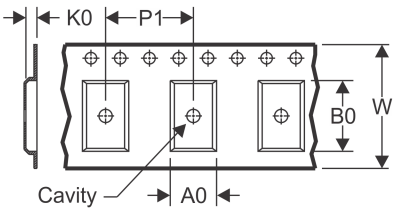
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

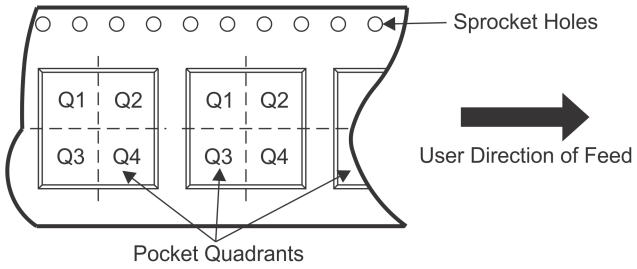


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

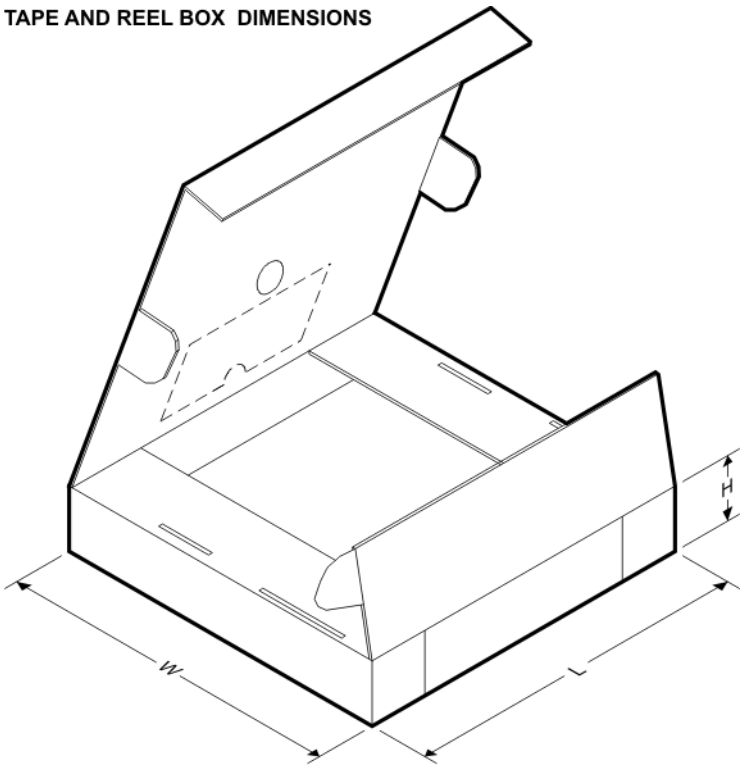
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS07DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS07DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



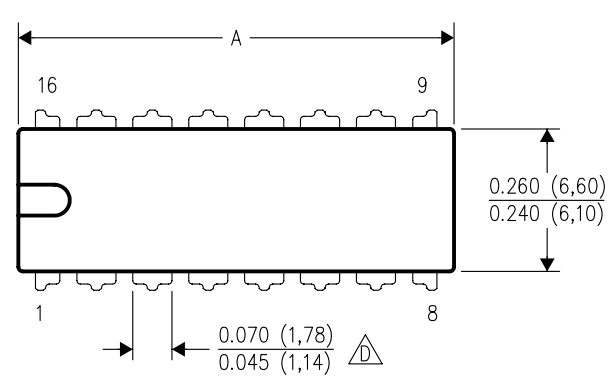
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS07DBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74LS07DR	SOIC	D	14	2500	367.0	367.0	38.0

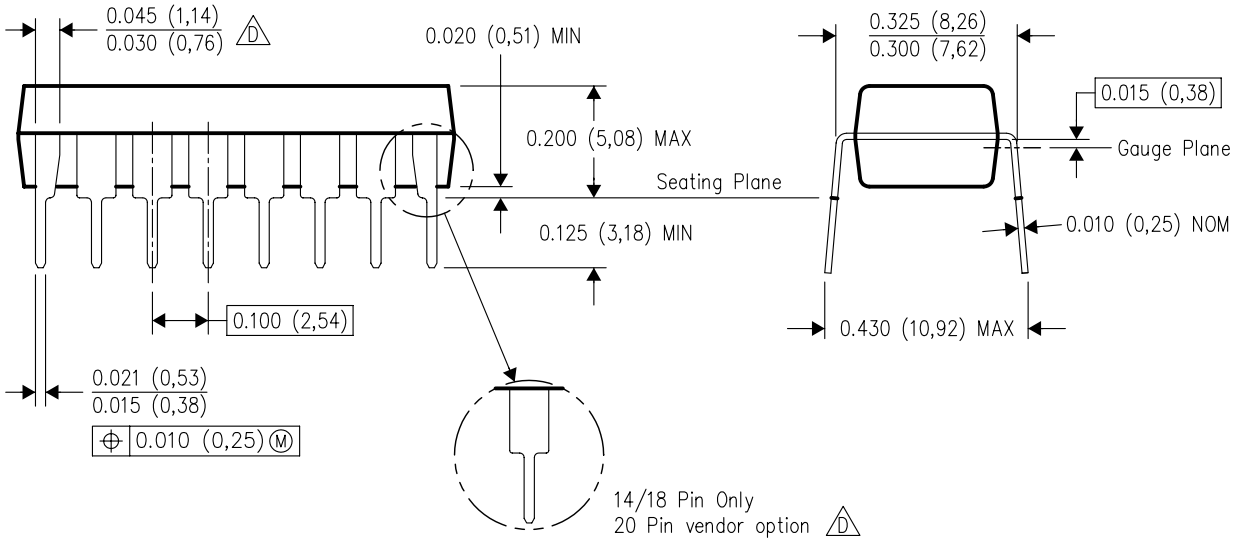
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



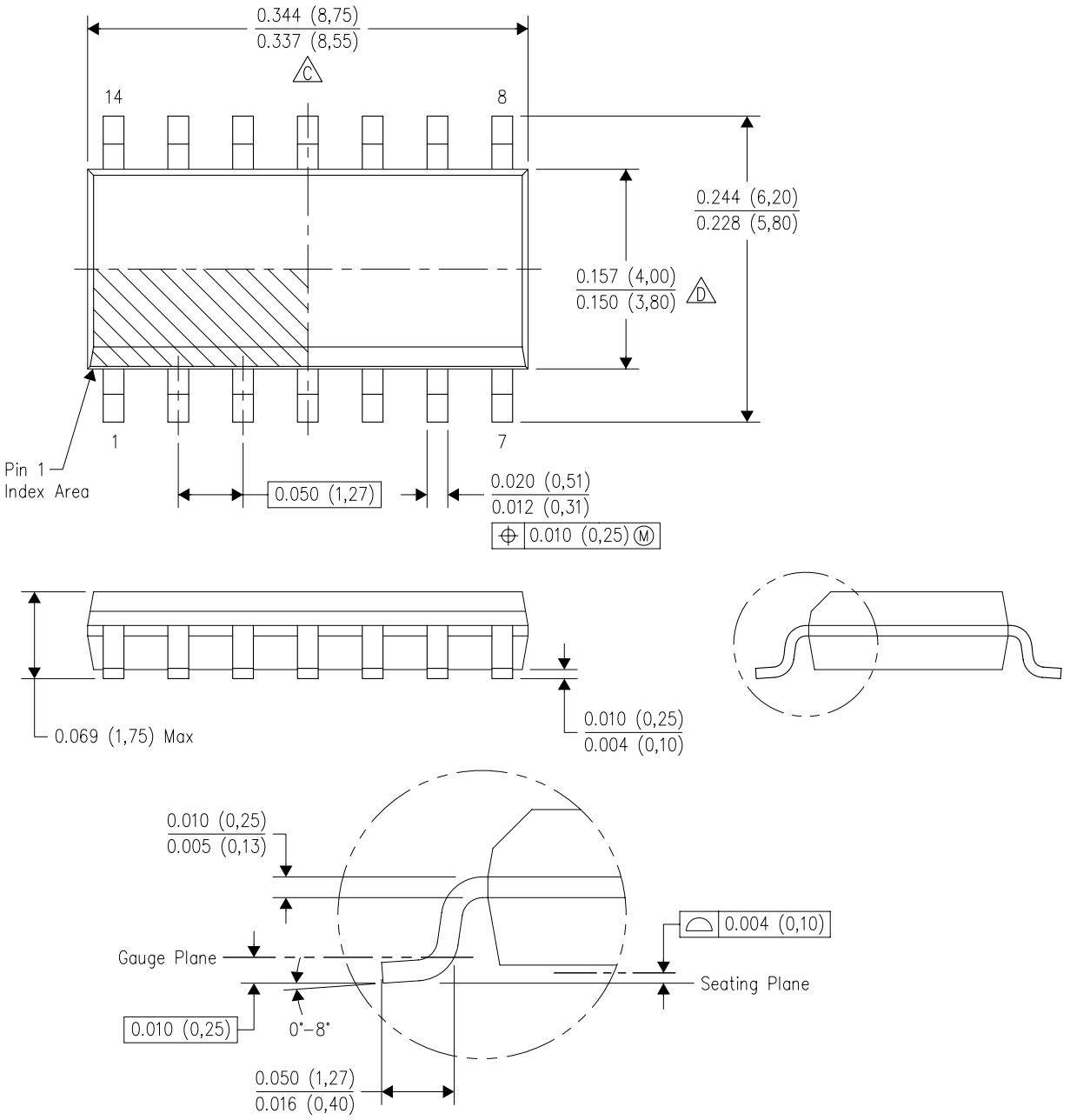
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

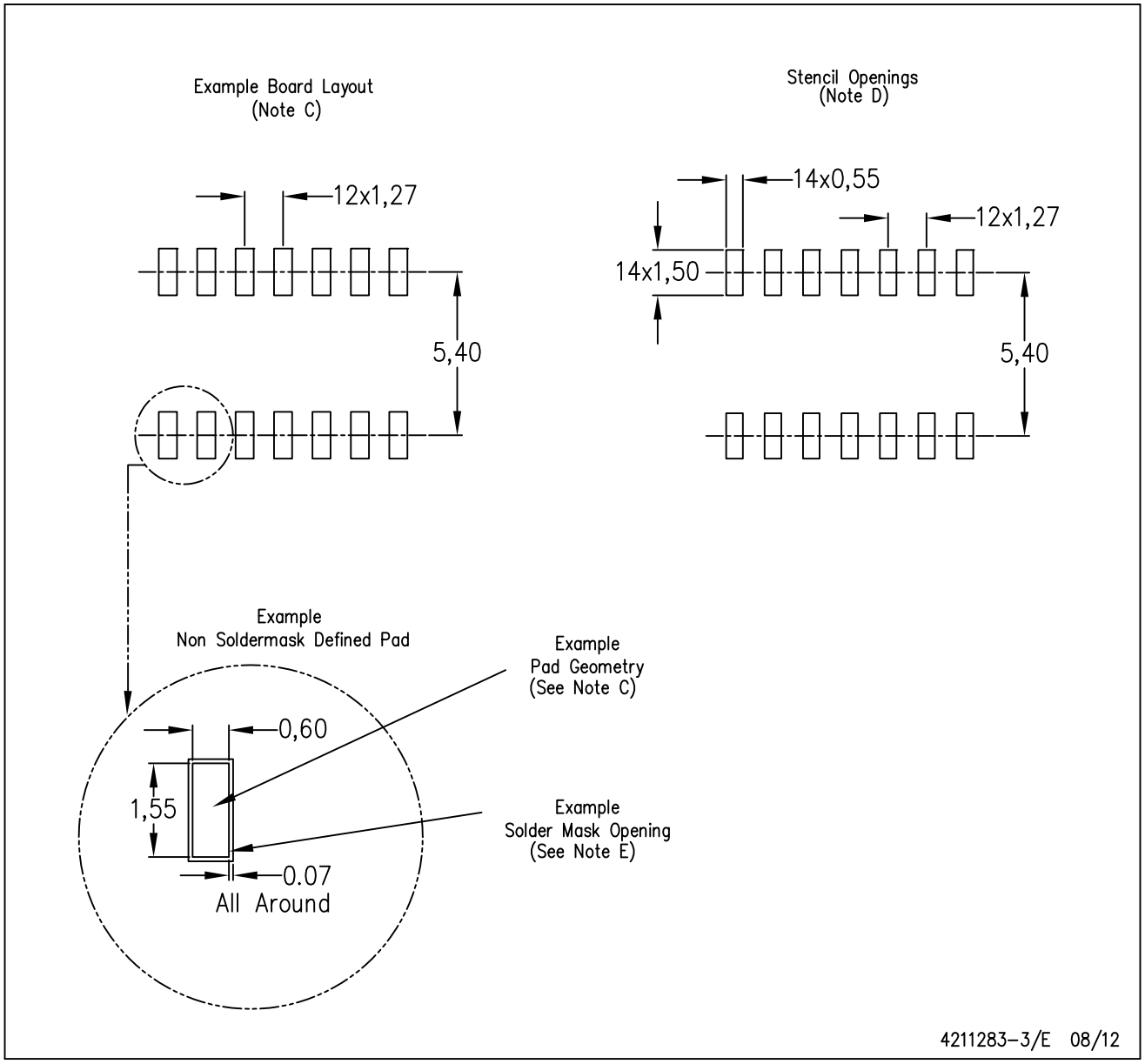
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE

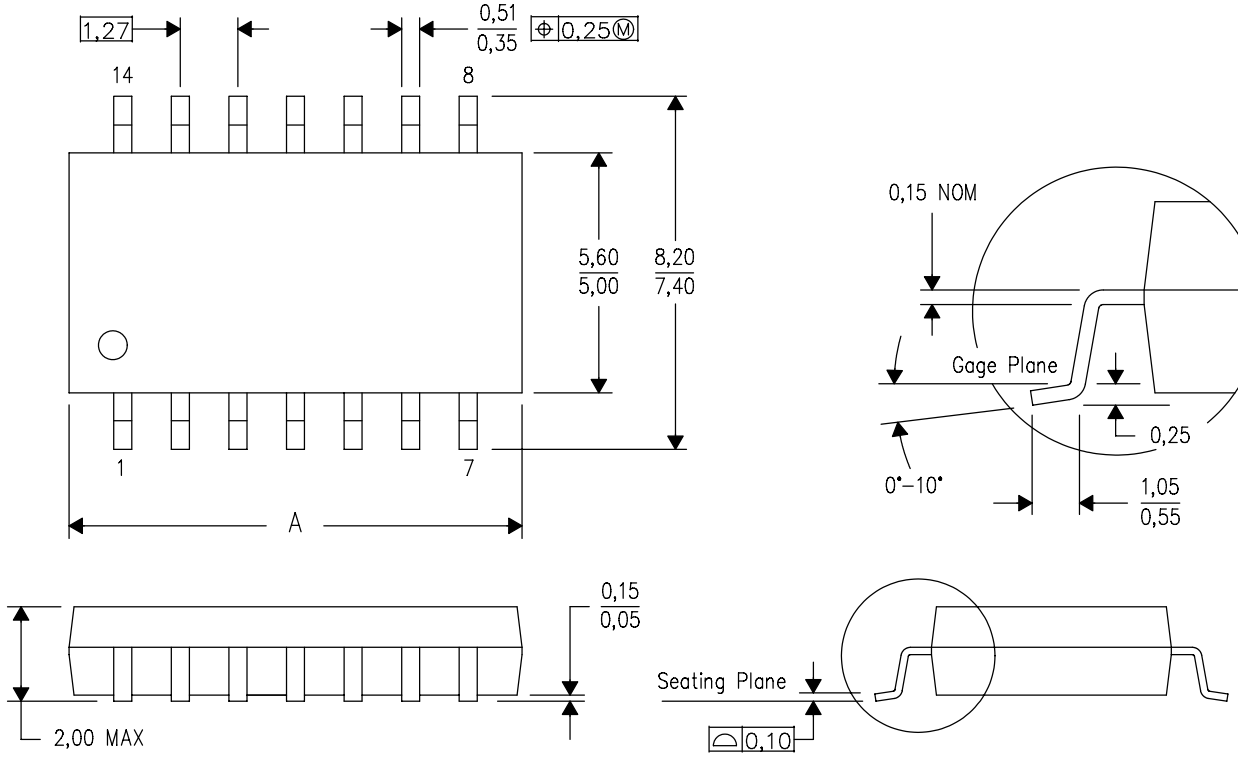


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

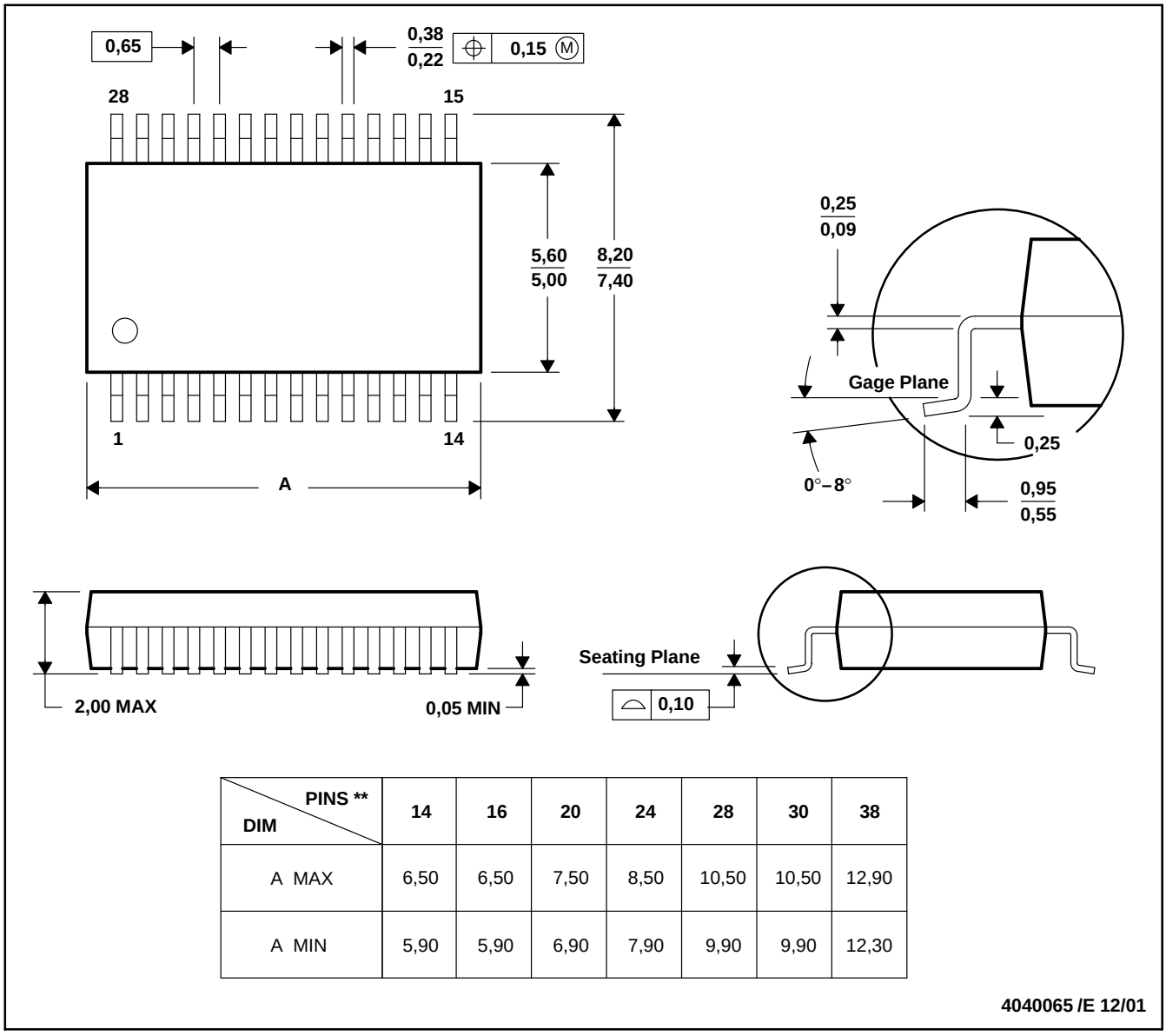
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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